

Absolute Maximum Ratings (Note 1)

Input Voltage	35V	Operating Junction Temperature	
Power Dissipation	Internally Limited	Hermetic (K and T Packages).....	150°C
Storage Temperature Range	-65°C to 150°C	Lead Temperature (Soldering, 10 Seconds)	300°C

Note 1. Exceeding these ratings could cause damage to the device.

Thermal Data

K Package:

Thermal Resistance - Junction to Case, θ_{JC} 3.0°C/W

Thermal Resistance - Junction to Ambient, θ_{JA} 35°C/W

T Package:

Thermal Resistance-Junction to Case, θ_{JC} 15°C/W

Thermal Resistance-Junction to Ambient, θ_{JA} 120°C/W

Note A. Junction Temperature Calculation: $T_J = T_A + (P_D \times \theta_{JA})$.

Note B. The above numbers for θ_{JC} are maximums for the limiting thermal resistance of the package in a standard mounting configuration. The θ_{JA} numbers are meant to be guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.

Recommended Operating Conditions (Note 2)

Input Voltage Range 7.0V to 25V

Operating Junction Temperature Range

Note 2. Range over which the device is functional.

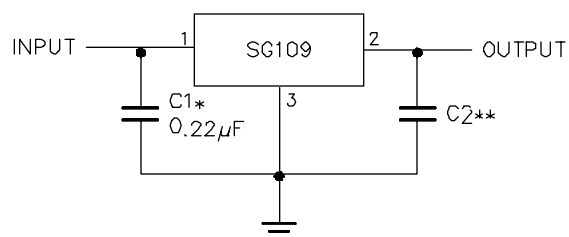
SG109 -55°C to 150°C

Electrical Characteristics

(Unless otherwise specified, these specifications apply over the operating ambient temperatures for SG109 with $-55^\circ\text{C} \leq T_A \leq 150^\circ\text{C}$ and for $V_{IN} = 10\text{V}$, $I_{OUT} = 500\text{mA}$ (K-package) and $I = 100\text{mA}$ (T-package). Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.)

Parameter	Test Conditions	SG109			Units
		Min.	Typ.	Max.	
Output Voltage	$T_A = 25^\circ\text{C}$	4.7	5.05	5.3	V
Line Regulation	$V_{IN} = 7.1\text{V to } 25\text{V}$, $T_A = 25^\circ\text{C}$		4.0	50	mV
Load Regulation	$T_A = 25^\circ\text{C}$				
	K-Package: $I_{OUT} = 5\text{mA to } 1.5\text{A}$		15	100	mV
	T-package: $I_{OUT} = 5\text{mA to } 500\text{mA}$		15	50	mV
Total Output Voltage Tolerance	$V_{IN} = 7.4\text{V to } 25\text{V}$				
	K-Package: $I_{OUT} = 5\text{mA to } 1.0\text{A}$, $P \leq 20\text{W}$	4.6	5.0	5.4	V
	T-package: $I_{OUT} = 5\text{mA to } 200\text{mA}$, $P \leq 2\text{W}$	4.6	5.0	5.4	V
Quiescent Current	$V_{IN} = 7.4\text{V to } 25\text{V}$			10	mA
Current Change	With Line : $V_{IN} = 7.4\text{V to } 25\text{V}$			0.5	mA
	With Load: K-Package: $I_{OUT} = 5\text{mA to } 1.0\text{A}$			0.8	mA
	T-package: $I_{OUT} = 5\text{mA to } 200\text{mA}$			0.8	mA
Output Noise Voltage	$f = 10\text{Hz to } 100\text{kHz}$, $T_A = 25^\circ\text{C}$		40		μV
Long Term Stability			10		mV
Ripple Rejection	$T_A = 25^\circ\text{C}$	50			dB

Application Circuits



* Required if regulator is in appreciable distance from power supply filter.

** Although no output capacitor is needed for stability it does improve transient response.

Figure 2 - Fixed 5V Regulator

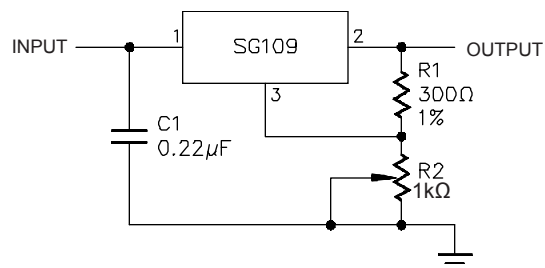
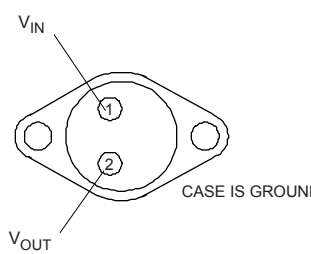
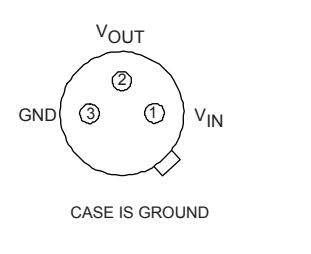


Figure 3 - Adjustable Output Regulator

Connection Diagrams and Ordering Information (See Notes Below)

Package	Part No.	Ambient Temperature Range	Connection Diagram
3-TERMINAL TO-3 METAL CAN K-PACKAGE	SG109K-883B SG109K	-55°C to 125°C -55°C to 125°C	
3-PIN TO-39 METAL CAN T-PACKAGE	SG109T-883B SG109T-JAN SG109T	-55°C to 125°C -55°C to 125°C -55°C to 125°C	

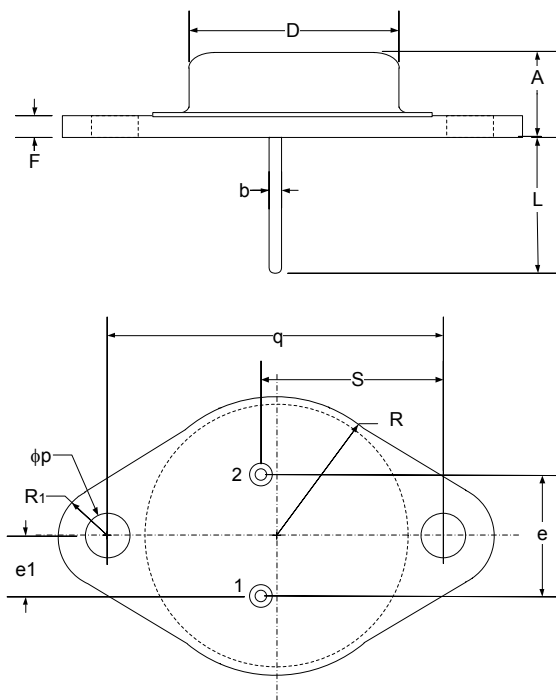
Note 1. Contact factory for JAN product availability.

2. All parts are viewed from the top.

3. Packages use Pb37/Sn63 hot solder lead finish, contact factory for availability of RoHS versions.

Package Outline Dimensions

Controlling dimensions are in inches, metric equivalents are shown for general information.

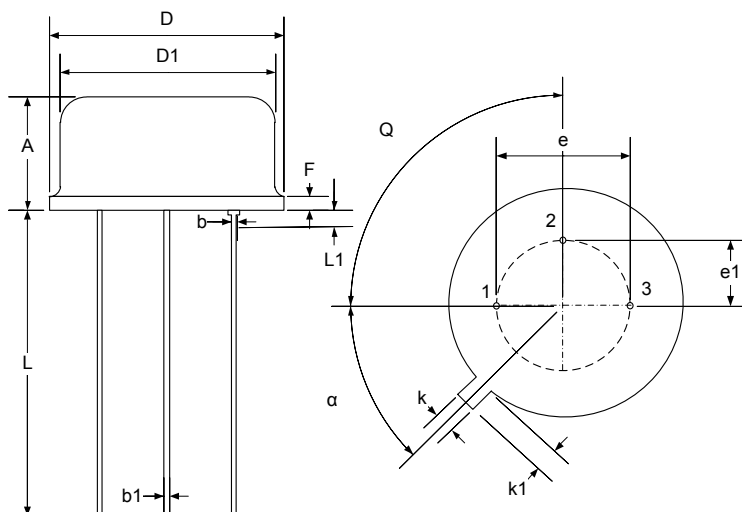


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.86	7.62	0.270	0.300
q	29.90	30.40	1.177	1.197
b	0.97	1.09	0.038	0.043
D	19.43	19.68	0.765	0.775
S	16.64	17.14	0.655	0.675
e	10.67	11.18	0.420	0.440
e1	5.21	5.72	0.205	0.225
F	1.52	2.03	0.060	0.080
ϕp	3.84	4.09	0.151	0.161
L	10.79	12.19	0.425	0.480
R1	3.33	4.78	0.131	0.188
R	12.57	13.34	0.495	0.525

Note:

Dimensions do not include protrusions; these shall not exceed 0.155mm (.006") on any side. Lead dimension shall not include solder coverage.

Figure 4 - K 3-Pin Metal Can TO-3 Package Dimensions



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.19	4.70	0.165	0.185
b	0.41	0.48	0.016	0.019
b1	0.41	0.53	0.016	0.021
D	8.89	9.40	0.350	0.370
D1	8.13	8.51	0.320	0.335
e	5.08 BSC		0.200 BSC	
e1	2.54 TYP		0.100 TYP	
F	-	1.02	-	0.040
k	0.71	0.86	0.028	0.034
k1	0.74	1.14	0.029	0.045
L	12.70	14.48	0.500	0.570
L1	-	1.27	-	0.050
Q	90° TYP		90° TYP	
α	45° TYP		45° TYP	

Note:

Dimensions do not include protrusions; these shall not exceed 0.155mm (.006") on any side. Lead dimension shall not include solder coverage.

Figure 5 - T 3-Pin Metal Can TO-39 Package Dimensions



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